501857739 03/19/2012

PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Chiang-Ming CHUANG	01/03/2012
Chun Che HUANG	01/10/2012
Shih-Chieh CHANG	01/10/2012

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park	
City:	Hsinchu	
State/Country:	TAIWAN	
Postal Code:	300	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13343940

CORRESPONDENCE DATA

 Fax Number:
 (703)518-5499

 Phone:
 7036841111

 Email:
 tsmc@ipfirm.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

via US Mail.

Correspondent Name: Lowe Hauptman Ham & Berner, LLP (TSMC)

Address Line 1: 1700 Diagonal Road, Suite 300 Address Line 4: Alexandria, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:	T5057-B589
NAME OF SUBMITTER:	Randy A. Noranbrock

Total Attachments: 1

source=efiledassgn2012-03-19#page1.tif

PATENT

REEL: 027885 FRAME: 0992

JF \$40.00 1334394

501857739

Docket No. T5057-B589

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Chiang-Ming CHUANG
- Chun Che HUANG
- Shih-Chieh CHANG

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

MULTILAYER BONDING PAD AND METHOD OF MAKING SAME

- for which an application for United States Letters Patent was filed on $\frac{2012-01-05}{2012-01-05}$, and identified by United States Patent Application No. $\frac{13/343,940}{2012-01-05}$; or (a)
- (b) for which an application for United States Letters Patent was executed on _____

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

Date: 20/2/1/10. Date: 20/2/1/10

PATENT REEL: 027885 FRAME: 0993

RECORDED: 03/19/2012